Record 12: JP8003384A

(ENG) RESIN COMPOSITION FOR FILM FOR FOOD PACKAGING AND FILM FOR FOOD PACKAGING

Assignee: SUMITOMO CHEMICAL CO

[no drawing available]

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Abstract: (ENG) <sec>PURPOSE: To obtain a resin composition having performances such as low-temperature heat sealability and food sanitation besides mechanical strength such as impact strength, tensile strength and tear strength required as a material for food packaging. CONSTITUTION: This resin composition is obtained by uniformly blending (A) 10-95wt.% of an ethylene/α- olefin copolymer comprising ethylene and maximum melt peak temperature by a differential scanning calorimeter with (B) 90-5wt.% of an ethylene/α-olefin copolymer comprising ethylene and a 3-12C α-olefin, having 0.880-0.920- g/cm<sp pos="post">3</sp>density, 1.3- 3.0 molecular weight distribution shown by the ratio of weight-average molecular weight/number-average molecular weight and 60-110°C maximum melt peak temperature in a molten state.

Priority Data: JP 14368094 19940624 A X;

IPC (International Class): C08L02308; C08J00518

